

Attorney Docket No. 245463US-2SXDIV
Inventor: Takeo Ito, et al.
Preliminary Amendment filed herewith

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-8 (Canceled).

Claim 9 (Original): A method of manufacturing an electron source device, comprising:
subjecting a metal substrate to electrolytic oxidation, thereby forming an oxide substrate
having a number of small through holes;
burying an electron-emitting material in the through holes of the oxide substrate;
forming a first electrode on one surface of the oxide substrate, said first electrode
contacting the electron-emitting material; and
forming a second electrode on another surface of the oxide substrate, said second
electrode insulated from the electron-emitting material.

Claim 10 (Original): The method of manufacturing an electron source device, according
to Claim 9, wherein an electrolysis voltage is controlled, in the electrolytic oxidation, to control
the diameter of the small through holes.

Claim 11 (Original): The method of manufacturing an electron source device, according
to Claim 9, wherein an electrolysis time is controlled, in the electrolytic oxidation, to control the
diameter of the small through holes.

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Claim 12 (Original): The method of manufacturing an electron source device, according to Claim 9, wherein the electron-emitting material is buried in the through holes by introducing an organic substance into the through holes and then baking the organic substance to carbonize the substance.

Claim 13 (Original): The method of manufacturing an electron source device, according to Claim 12, wherein the oxide substrate is coated with an mold release agent before the organic substance is introduced.

Claim 14 (Original): The method of manufacturing an electron source device, according to Claim 9, wherein the electron-emitting material is buried in the through holes by vapor-depositing an organic substance in the through holes.

Claims 15-18 (Canceled).